



IEEE World Haptics Conference 2019

Tokyo

DATE July 9 to 12, 2019
VENUE sola city Conference Center, Tokyo, JAPAN
CONTACT contact@worldhaptics2019.org

<http://worldhaptics2019.org/>

CONFERENCE TOPICS

- Haptic interface design and control
- Tactile displays
- Sensors and actuators
- Human-computer interaction
- Multi-modal systems
- Virtual and augmented reality
- Haptic rendering and modeling
- Embedded haptics
- Teleoperation
- Shared control and collaboration
- Robotic manipulation
- Physical human-robot interaction
- Human haptic perception
- Neuroscience of touch
- Haptics in industrial and commercial applications
- Haptics in medical applications
- Haptics in art and design applications
- Other innovative applications of haptics

Introduction

Welcome to the IEEE World Haptics Conference 2019, the 8th Joint Eurohaptics Conference and the IEEE Haptics Symposium.

The IEEE World Haptics Conference is the premier international conference covering all aspects of haptics, covering the basic scientific findings, technological developments, algorithms and applications. It is a central venue for reporting research results and demonstrating novel capabilities in the field of haptics. The conference will offer opportunities to share the most up-to-date scientific discoveries and innovative products.

The ultimate objective is to advance the field of haptics through networking among academia, industry, and affiliated specialists; and to build mutual understanding among colleagues from all over the world.

We look forward to meeting you in Tokyo from July 9 to 12, 2019. We anticipate that with your active participation and support, the conference will be a resounding success.



Important Dates

December 21, 2018

CCC / Workshop
Proposals Submission

February 6, 2019

Technical Paper
Submission

April 19, 2019

Work in Progress /
Hands-on Demos /
Design Showcase
Submission

May 10, 2019

Work-in-Progress /
Hands-on Demos /
Design Showcase
Notification

January 25, 2019

Student Innovation
Challenge VR Proposal
Submission

April 1, 2019

Student Volunteers
Applications Deadline

May 1, 2019

Student Volunteers
Acceptance Notification

Early May, 2019

Early Registration

February 3, 2019

Student Innovation
Challenge Mobility Proposal
Submission

April 5, 2019

Paper Acceptance
Notification

May 7, 2019

Camera-Ready
Paper Submission

July 9-12, 2019

Conference

Committee

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Hiroyuki Kajimoto (University of Electro-Communications, Japan)

Program Chair

Hiroaki Yano (University of Tsukuba, Japan)

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